## Solderless Breadboard





## **Specifications**

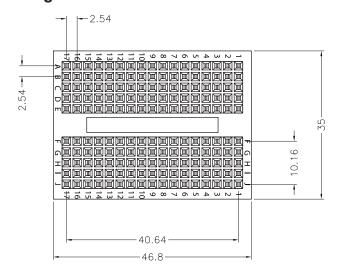
Board Type : Prototype Board Total Number of Tie Points : 170 Tie Points

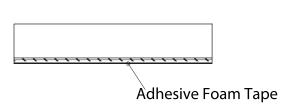
Board Material : Epoxy Glass Composite

No. of Terminal Strips : 1 Terminal Strip
Board Dimensions (L × W) : 46.8mm × 35mm

Pitch : 2.54mm

## Diagram





## **Part Number Table**

Description	Part Number
Breadboard, with Buckle 170 Tie Points, 46.8mm × 35mm, White	21-18964

**Dimensions: Millimetres** 

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